

**Amendments to the Claims**

1. (CURRENTLY AMENDED) A lead-frame configuration (60) that is strip-like in form, that has a frame base (3) and that has a plurality of lead-frames (6, 7, 8, 9, 10, 11) that are connected to the frame base (3) and that are situated next to one another in the longitudinal direction (2) of the strip, each of which lead-frames (6, 7, 8, 9, 10, 11) is intended to receive a chip (41, 42, 43, 44, 45, 46), wherein each lead-frame (6, 7, 8, 9, 10, 11) has at least two connecting plates (12, 13), wherein there being is provided for the lead-frames (6, 7, 8, 9, 10, 11) that are situated next to one another in the longitudinal direction (2) of the lead-frame strip a reinforcement strip (66, 67) that extends in the longitudinal direction (2) of the strip and is connected both to the frame base (3) and to the connecting plates (12, 13) of each of the lead-frames (6, 7, 8, 9, 10, 11) that are situated next to one another in the longitudinal direction (2) of the lead-frame strip, the connection being made by means of a layer (73) of adhesive, wherein the reinforcement strip (66, 67) is formed by a fiber-reinforced film of plastics material and wherein the layer (73) of adhesive is produced by means of an adhesive that is suitable for transmitting shear forces that may possibly occur in the region between the connecting plates (12, 13) on the one hand and the reinforcement strip (66, 67) on the other hand.
2. (ORIGINAL) A lead-frame configuration as claimed in claim 1, wherein at least one further layer is provided on the reinforcement strip formed by a fiber-reinforced film of plastics material.
3. (CURRENTLY AMENDED) A lead-frame configuration (60) as claimed in claim 2, wherein at least one further layer is provided on the reinforcement strip formed by a fiber-reinforced film of plastics material, which at least one further layer belongs to the group of layers detailed below, which group comprises: a protective layer that is composed of metal, a damping layer that is composed of a damping material and preferably of a paper-like material, and a fastening layer that is composed of a fastening material and preferably of an adhesive material.

4. (CURRENTLY AMENDED) A module (70)-that is produced with the help of a lead-frame configuration (60)-and that has at least two connecting plates (12, 13) each of which is connected to a connecting contact (47, 48) of a chip (41), and that has a reinforcement ribbon (71)-that is connected to the connecting plates (12, 13), the connection being made by means of a layer (73)-of adhesive, wherein the reinforcement ribbon (71)-is formed by a fiber-reinforced film of plastics material and wherein the layer (73)-of adhesive is produced by means of an adhesive that is suitable for transmitting shear forces that may possibly occur in the region between the connecting plates (12, 13) on the one hand and the reinforcement ribbon (71)-on the other hand.

5. (CURRENTLY AMENDED) A module (70)-as claimed in claim 4, wherein at least one further layer (74, 75, 76)-is provided on the reinforcement ribbon (71)-formed by a fiber-reinforced film of plastics material.

6. (CURRENTLY AMENDED) A module (70)-as claimed in claim 5, wherein at least one further layer (74, 75, 76)-is provided on the reinforcement ribbon (71)-formed by a fiber-reinforced film of plastics material, which at least one further layer belongs to the group of layers (74, 75, 76)-detailed below, which group comprises: a protective layer (74)-that is composed of metal, a damping layer (75)-that is composed of a damping material and preferably of a paper-like material, and a fastening layer (76)-that is composed of a fastening material and preferably of an adhesive material.

7. (CURRENTLY AMENDED) A data carrier (72), wherein the data carrier (72)-contains a module as claimed in ~~any of claims 4 to 6~~claim 4.